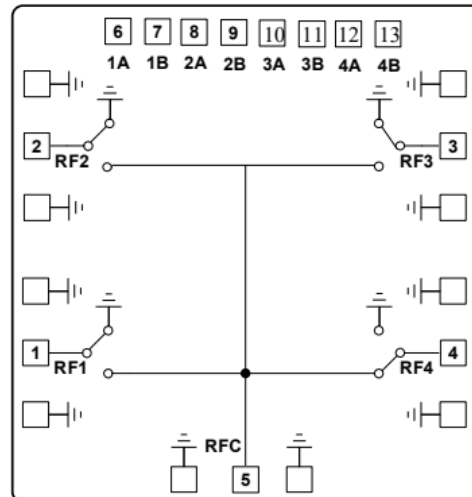


**Features**

- SP4T Reflective design
- Isolation: 31dB
- Insertion Loss: 2.0dB
- Input P-0.1: 48dBm@ 0.1GHz
- Input P-0.3: 42dBm@ 6GHz
- Switching Time: 20ns
- Input/Output: 50 Ohm matched
- Die Size: 2.00x2.00x 0.1 mm

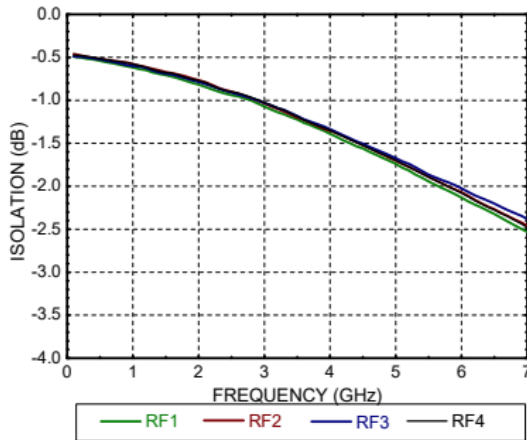
**Typical Applications**

- TTL compatible driver included
- Fast Switching Speed
- Low Insertion Loss and High Isolation
- Customization available upon request

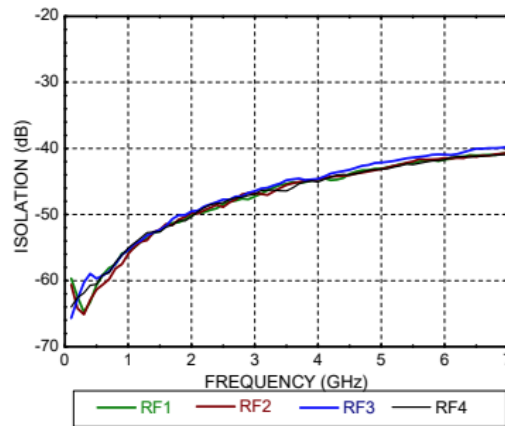
**Functional Block Diagram**

**Electrical Specifications**
**TA = +25°C, VCTL=0/-40V**

Parameters	Min.	Typ.	Max.	Units
<b>Frequency</b>	<b>0.1-6</b>			<b>GHz</b>
<b>Insertion Loss</b>		<b>2.0</b>		<b>dB</b>
<b>On-state Return Loss(RFC)</b>		<b>10</b>		<b>dB</b>
<b>On-state Return Loss(RF1/RF2)</b>		<b>10</b>		<b>dB</b>
<b>Off-state Return Loss</b>		<b>2</b>		<b>dB</b>
<b>Off-state Isolation</b>		<b>40</b>		<b>dB</b>
<b>Input power 0.1dB Compression@0.1GHz</b>		<b>48</b>		<b>dBm</b>
<b>Input power 0.3dB Compression@6GHz</b>		<b>42</b>		<b>dBm</b>
<b>Switching Time</b>		<b>20</b>		<b>ns</b>

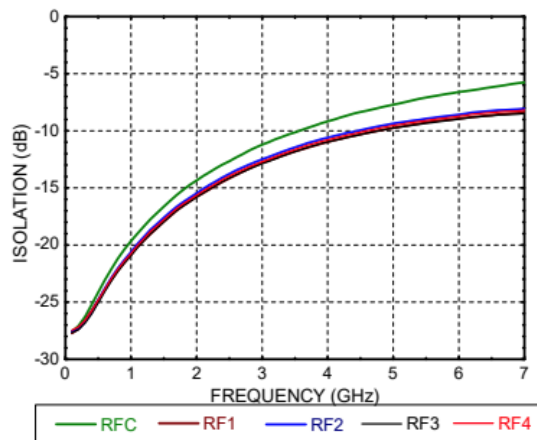
Insertion Loss



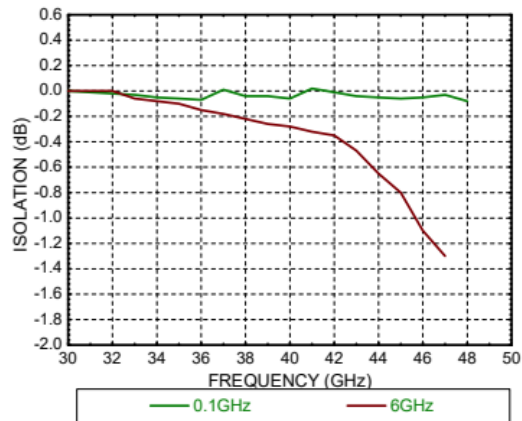
Isolation



Return Loss (ON State)

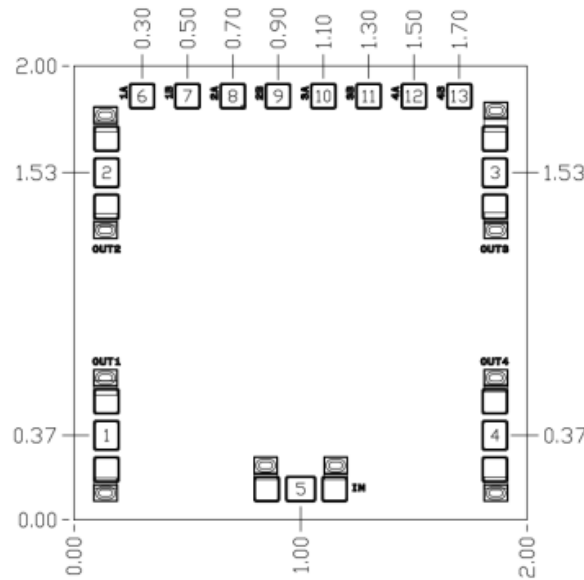


Insertion Loss Compression vs Input Power (Normalized)





**Outline Drawing:**  
All Dimensions in mm



**Pad Description**

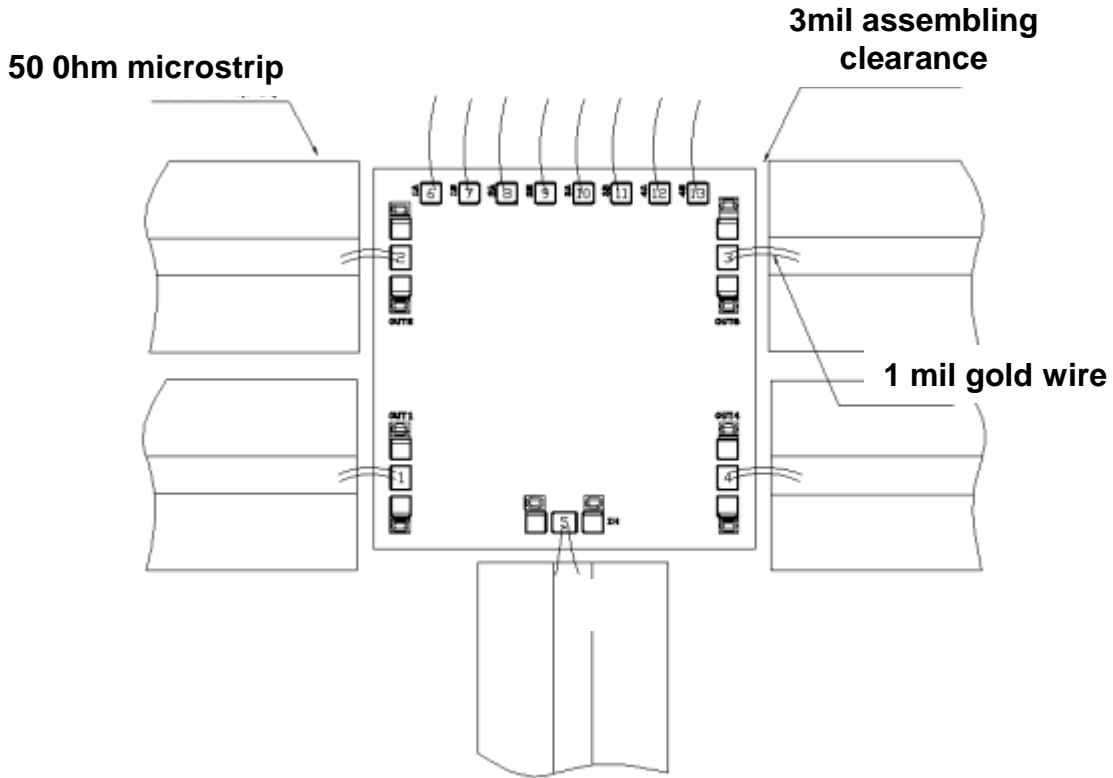
PAD	Function	Description
5	RFC	The pad is DC coupling and matched to 50Ω. If RF voltage is not 0V, then blocking capacitor is required externally.
1-4	RF1-RF4	The pad is DC coupling and matched to 50Ω. If RF voltage is not 0V, then blocking capacitor is required externally.
6-13	1A-4B	0/-40 V Control Pad
Die Bottom	GND	Die bottom must be connected to RF/DC ground.

**True Table**

1A	1B	2A	2B	3A	3B	4A	4B	state
0V	-40V	-40V	0V	-40V	0V	-40V	0V	RF1 ON
-40V	0V	0V	-40V	-40V	0V	-40V	0V	RF2 ON
-40V	0V	-40V	0V	0V	-40V	-40V	0V	RF3 ON
-40V	0V	-40V	0V	-40V	0V	0V	-40V	RF4 ON



### Assembly Drawing



#### Notes:

1. Die thickness: 100um
2. Typical bond pad is 100\*100  $\mu\text{m}^2$
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads

#### Maximum Ratings:

1. Control voltage: -50V
2. Control current: 2mA
3. Maximum input power: +47dBm  
(Continuous wave, 50 $\Omega$ , withstands for 20 minutes)
4. Storage temperature: -65°C to +150°C
5. Operating temperature: -55°C to +85°C